

BONDING THE STARS

FMS
BONDTEC



5830

Thin-Wire Wedge Bonder

Bond System

Wire types	Aluminium und Goldwire 17,5 ... 75 μm on 2"-Spool, motorized wire despooler (optional)
Bond head	Wedge-Wedge for thin wire Standard wedges of 1" length,
Ultrasonic System	F&K Generator 60/100 kHz further frequenzies on request

Bonder Base

Axes	Working area X/Y-axis 200 x 150 mm; step resolution 0,3 μm Programmable Z axis with 100 mm stroke; step resolution 0,3 μm
Hardware	Dual-Core PC with Windows 7 OS, Ethernet, USB 2.0/3.0, LCD Colour Display 22" GigE-CCD-Colour Camera, 5 Mpixel Fully networkable in TCP/IP servers for program archiving
Software	From single bonds up to complex programmes, teach-in programming, also in step-and-repeat Loop shapes can be stored in libraries Optionally: pattern recognition with pseudo-error check

The Thin-Wire version of the automatic wire bonders in our Series 58 featuring exchangeable bond heads.

A fully automatic mode makes it ideally suited for medium-scale production. Parts to be bonded are fed manually by the operator, but the bonds are produced completely without operator influence. Thanks to the built-in pattern recognition.

Single bonds can be made within seconds, making the machine perfect for R&D and pilot manufacturing and medium volume production.

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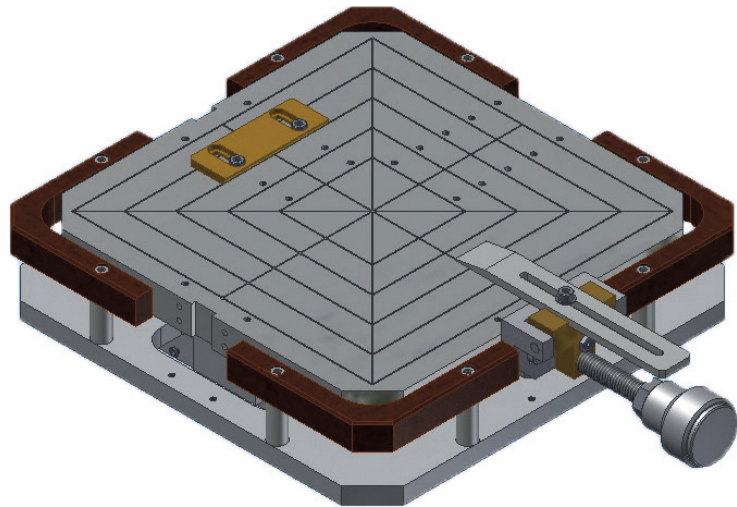
F&S BONDTEC

Dimensions
Connections

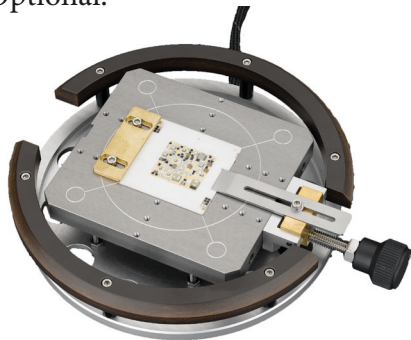
W x D x H 92 x 71 x 65 cm, weight approx. 80 kg
100...240 VAC, single phase, 50/60 Hz,
max. 230 VA
Ø 6 mm standard vacuum tubing

Workholder

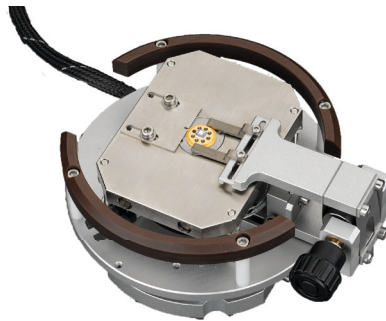
Standard-Workholder
for Parts up to 6" x 6"
mit Vacuum und mechanical clamping



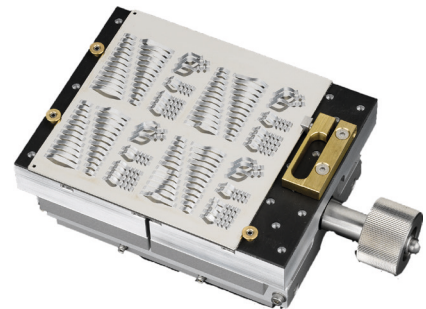
Optional:



for parts up to 4x4"
with vacuum and
mechanical clamping



TO workholder with
mechanical clamping



4x4" workholder with rubberized
surface and mechanical clamping



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